

SSC8041GN4

P-Channel Enhancement Mode MOSFET

> Features

V _{DS}	V _{GS}	R _{DS(ON)}	ID
-40V	±20V	9mΩ@-10V	-36A
	<u> </u>	16mΩ@-4V5	-304

> Description

This SSC8041GN4 uses advanced trench technology to provide excellent RDSON and low gate charge. The complementary MOSFETS may be used to form a level shifted high side switch, and for a host of other applications.

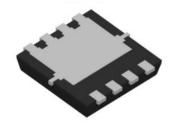
100% UIS + ΔVDS + Rg Tested!

- > Applications
- Load Switch
- PWM Application
- Power Management

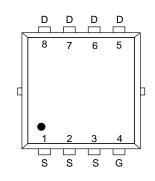
> Ordering Information

Device	Package	Shipping
SSC8041GN4	PDFN3.3X3.3-8L	5000/Reel

Pin configuration



PDFN3.3X3.3-8L (Bottom View)



Pin Configuration (Top View)



(YW: Internal Traceability Code)





Symbol	Parameter	Ratings	Unit	
V _{DSS}	Drain-to-Source Voltage		-40	V
V _{GSS}	Gate-to-Source Volta	Gate-to-Source Voltage		
	Continuous Droin Current d	Tc=25℃	-36	
ID	Continuous Drain Current ^d	Tc=100℃	-20.4	A
	Continuous Drain Current ^a	T _A =25℃	-14	
DSM		T ,= 70 ℃	-10.7	A
IDM	Pulsed Drain Current ^b		-144	A
5	Power Dissipation °	Tc=25℃	21	
PD		Tc=100℃	8.3	W
P _{DSM}		T _A =25℃	3.13	w
	Power Dissipation ^a	T ,= 70 ℃	2	
las	Avalanche Current ^b L=0.5mH \$	-17	A	
Eas	Avalanche Energy ^b L=0.5mH Single Pulse		72.3	mJ
TJ	Operation junction temperature		-55~150	°C
Tstg	Storage temperature ra	-55~150	Ĉ	

> Absolute Maximum Ratings ($T_A=25^{\circ}$ unless otherwise noted)

> Thermal Resistance Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R _{0JA}	Junction-to-Ambient Thermal Resistance ^a	40	°C/W
R _{θJC}	Junction-to-Case Thermal Resistance	6	C/W

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25 °C.The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.





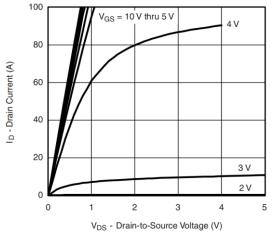
> Electrical Characteristics (T_A=25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V _(BR) DSS	$V_{GS} = 0V, I_D = -250 \mu A$	-40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250 uA$	-1.2	-2.1	-3	V
Drain Source On Registeres	Brack	$V_{GS} = -10V, I_D = -20A$		9	13	mΩ
Drain-Source On-Resistance	R _{DS(on)}	$V_{GS} = -4.5V, I_D = -10A$		16	23	
Zero Gate Voltage Drain Current	Idss	$V_{DS} = -40V, V_{GS} = 0V$			1	μA
Gate-Source Leak Current	lgss	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			±100	nA
Transconductance	G _{FS}	$V_{DS} = -15V, I_D = -12A$		40		S
Forward Voltage	Vsd	$V_{GS} = 0V$, $I_S = -5A$			1.4	V
Gate Resistance	Rg	$V_{DS} = 0V, f = 1MHz$		4		Ω
Input Capacitance	Ciss			2500		pF
Output Capacitance	Coss	$V_{DS} = -20V, V_{GS} = 0V,$ f = 1MHz		250		
Reverse Transfer Capacitance	Crss			230		
Total Gate Charge	Q _G			18		
Gate to Source Charge	Q _{GS}	V _{GS} = -10V, V _{DS} = -20V, I _D = -15A		5		nC
Gate to Drain Charge	Q _{GD}	1D = -15A		6		
Turn-on Delay Time	T _{D(ON)}			12		
Rise Time	Tr	$V_{GS} = -10V, V_{DS} = -10V,$		12		
Turn-off Delay Time	T _{D(OFF)}	$R_L = 10\Omega, R_G = 1\Omega,$		23		ns
Fall Time	T _f			9		
Diode Recovery Time	Trr	I⊧=-20A, di/dt=500A/us		20		ns
Diode Recovery Charge	Qrr	I _F =-20A, di/dt=500A/us		18		nC

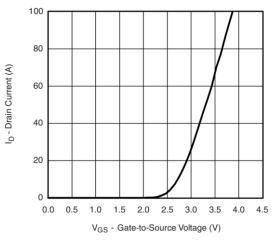


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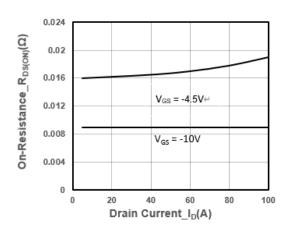
> Typical Performance Characteristics ($T_A=25^{\circ}C$ unless otherwise noted)



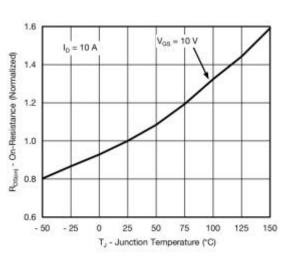
Output Characteristics



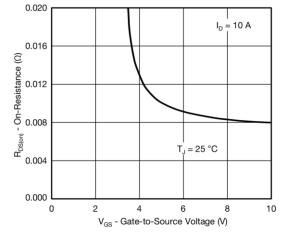
Transfer Characteristics



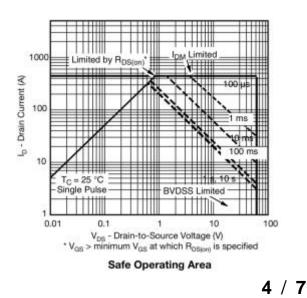
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

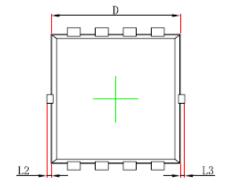


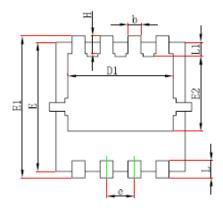
Analog Future





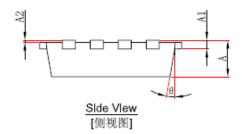
Package Information







<u>Bottom Vlew</u> [背视图]

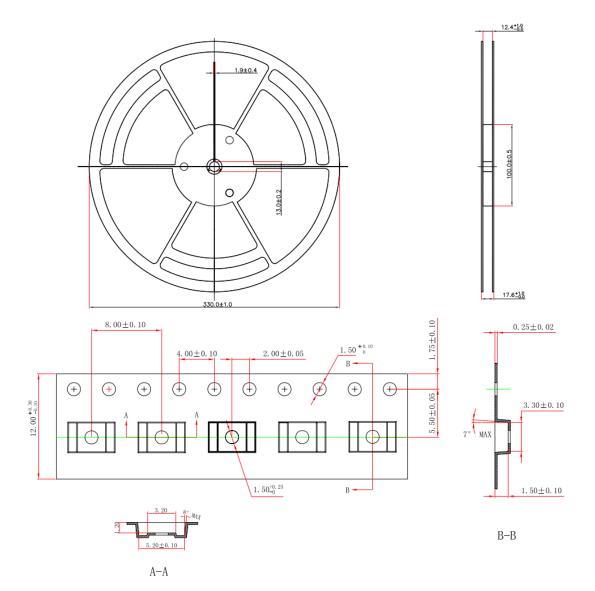


Package: PDNF3.3X3.3-8L

Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	0.650	0.850	0.026	0.033	
A1	0.152	REF.	0.006 REF.		
A2	0~0).05	0~0	.002	
D	2.900	3.100	0.114	0.122	
D1	2.300	2.600	0.091	0.102	
E	2.900	3.100	0.114	0.122	
E1	3.150	3.450	0.124	0.136	
E2	1.535	1.935	0.060	0.076	
b	0.200	0.400	0.008	0.016	
e	0.550	0.750	0.022	0.030	
L	0.300	0.500	0.012	0.020	
L1	0.180	0.480	0.007	0.019	
L2	0~0.100		0~0	.004	
L3	0~0.100		0~0	.004	
Н	0.315	0.515	0.012	0.020	
θ	9°	13°	9°	13°	



> Tape and Reel





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